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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	60 MIPs
Connectivity	CANbus, I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	25
Program Memory Size	64KB (22K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	A/D 13x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	36-UFQFN Exposed Pad
Supplier Device Package	36-UQFN (5x5)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ev64gm103-e-m5

2.5 ICSP Pins

The PGECx and PGEDx pins are used for ICSP and debugging purposes. It is recommended to keep the trace length between the ICSP connector and the ICSP pins on the device as short as possible. If the ICSP connector is expected to experience an ESD event, a series resistor is recommended, with the value in the range of a few tens of Ohms, not exceeding 100 Ohms.

Pull-up resistors, series diodes and capacitors on the PGECx and PGEDx pins are not recommended as they will interfere with the programmer/debugger communications to the device. If such discrete components are an application requirement, they should be removed from the circuit during programming and debugging. Alternatively, refer to the AC/DC characteristics and timing requirements information in the respective device Flash programming specification for information on capacitive loading limits and pin Voltage Input High (V_{IH}) and Voltage Input Low (V_{IL}) requirements.

Ensure that the "Communication Channel Select" (i.e., PGECx/PGEDx pins) programmed into the device matches the physical connections for the ICSP to MPLAB® PICkit™ 3, MPLAB ICD 3 or MPLAB REAL ICE™.

For more information on MPLAB ICD 2, ICD 3 and REAL ICE connection requirements, refer to the following documents that are available on the Microchip web site (www.microchip.com).

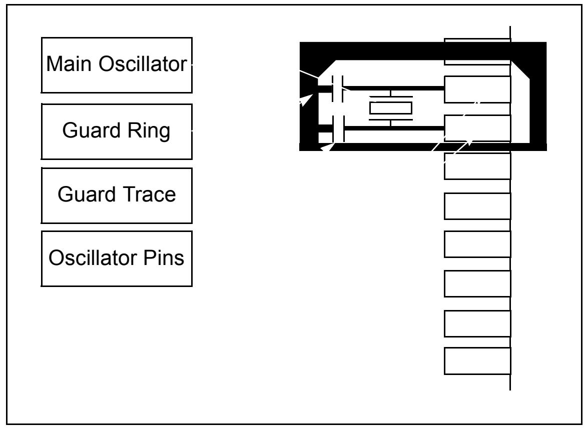
- *"Using MPLAB® ICD 3"* (poster) (DS51765)
- *"MPLAB® ICD 3 Design Advisory"* (DS51764)
- *"MPLAB® REAL ICE™ In-Circuit Emulator User's Guide"* (DS51616)
- *"Using MPLAB® REAL ICE™ In-Circuit Emulator"* (poster) (DS51749)

2.6 External Oscillator Pins

Many DSCs have options for at least two oscillators: a high-frequency primary oscillator and a low-frequency secondary oscillator. For more information, see **Section 9.0 "Oscillator Configuration"**.

The oscillator circuit should be placed on the same side of the board as the device. Also, place the oscillator circuit close to the respective oscillator pins, not exceeding one-half inch (12 mm) distance between them. The load capacitors should be placed next to the oscillator itself, on the same side of the board. Use a grounded copper pour around the oscillator circuit to isolate them from surrounding circuits. The grounded copper pour should be routed directly to the MCU ground. Do not run any signal traces or power traces inside the ground pour. Also, if using a two-sided board, avoid any traces on the other side of the board where the crystal is placed as shown in Figure 2-3.

FIGURE 2-3: SUGGESTED PLACEMENT OF THE OSCILLATOR CIRCUIT



2.7 Oscillator Value Conditions on Device Start-up

If the PLL of the target device is enabled and configured for the device start-up oscillator, the maximum oscillator source frequency must be limited to 5 MHz < F_{IN} < 13.6 MHz to comply with device PLL start-up conditions. This intends that, if the external oscillator frequency is outside this range, the application must start up in the FRC mode first. The default PLL settings after a POR with an oscillator frequency outside this range will violate the device operating speed.

Once the device powers up, the application firmware can initialize the PLL SFRs, CLKDIV and PLLFBD, to a suitable value, and then perform a clock switch to the Oscillator + PLL clock source.

Note:	Clock switching must be enabled in the device Configuration Word.

2.8 Unused I/Os

Unused I/O pins should be configured as outputs and driven to a logic low state.

Alternatively, connect a 1k to 10k resistor between V_{SS} and unused pins, and drive the output to logic low.

4.2.5 X AND Y DATA SPACES

The dsPIC33EVXXXGM00X/10X family core has two Data Spaces: X and Y. These Data Spaces can be considered either separate (for some DSP instructions) or as one unified, linear address range (for MCU instructions). The Data Spaces are accessed using two Address Generation Units (AGUs) and separate data paths. This feature allows certain instructions to concurrently fetch two words from RAM, thereby enabling efficient execution of DSP algorithms, such as Finite Impulse Response (FIR) filtering and Fast Fourier Transform (FFT).

The X DS is used by all instructions and supports all addressing modes. The X DS has separate read and write data buses. The X read data bus is the read data path for all instructions that view the DS as combined X and Y address space. It is also the X data prefetch path for the dual operand DSP instructions (`MAC` class).

The Y DS is used in concert with the X DS by the `MAC` class of instructions (`CLR`, `ED`, `EDAC`, `MAC`, `MOVSAC`, `MPY`, `MPY.N` and `MSC`) to provide two concurrent data read paths.

Both the X and Y Data Spaces support Modulo Addressing mode for all instructions, subject to addressing mode restrictions. Bit-Reversed Addressing mode is only supported for writes to the X Data Space.

All data memory writes, including in DSP instructions, view Data Space as combined X and Y address space. The boundary between the X and Y Data Spaces is device-dependent and is not user-programmable.

TABLE 4-22: PMD REGISTER MAP FOR dsPIC33EVXXXGM00X/10X FAMILY DEVICES

SFR Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
PMD1	0760	T5MD	T4MD	T3MD	T2MD	T1MD	—	PWMMD	—	I2C1MD	U2MD	U1MD	SPI2MD	SPI1MD	—	C1MD(1)	AD1MD	0000
PMD2	0762	—	—	—	—	IC4MD	IC3MD	IC2MD	IC1MD	—	—	—	—	OC4MD	OC3MD	OC2MD	OC1MD	0000
PMD3	0764	—	—	—	—	—	CMPMD	—	—	—	—	—	—	—	—	—	—	0000
PMD4	0766	—	—	—	—	—	—	—	—	—	—		—	REFOMD	CTMUMD	—	—	0000
PMD6	076A	—	—	—	—	—	PWM3MD	PWM2MD	PWM1MD	—	—	—	—	—	—	—	—	0000
PMD7	076C	—	—	—	—	—	—	—	—	—	—	—	DMA0MD DMA1MD DMA2MD DMA3MD	—	—	—	—	0000
PMD8	076E	—	—	—	SENT2MD	SENT1MD	—	—	DMTMD	—	—	—	—	—	—	—	—	0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: This feature is available only on dsPIC33EVXXXGM10X devices.

REGISTER 8-1: DMAxCON: DMA CHANNEL x CONTROL REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	U-0	U-0
CHEN	SIZE	DIR	HALF	NULLW	—	—	—
bit 15							bit 8

U-0	U-0	R/W-0	R/W-0	U-0	U-0	R/W-0	R/W-0
—	—	AMODE1	AMODE0	—	—	MODE1	MODE0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **CHEN:** DMA Channel Enable bit
1 = Channel is enabled
0 = Channel is disabled

bit 14 **SIZE:** DMA Data Transfer Size bit
1 = Byte
0 = Word

bit 13 **DIR:** DMA Transfer Direction bit (source/destination bus select)
1 = Reads from RAM address, writes to peripheral address
0 = Reads from peripheral address, writes to RAM address

bit 12 **HALF:** DMA Block Transfer Interrupt Select bit
1 = Initiates interrupt when half of the data has been moved
0 = Initiates interrupt when all of the data has been moved

bit 11 **NULLW:** Null Data Peripheral Write Mode Select bit
1 = Null data write to peripheral in addition to RAM write (DIR bit must also be clear)
0 = Normal operation

bit 10-6 **Unimplemented:** Read as ‘0’

bit 5-4 **AMODE<1:0>:** DMA Channel Addressing Mode Select bits
11 = Reserved
10 = Peripheral Indirect mode
01 = Register Indirect without Post-Increment mode
00 = Register Indirect with Post-Increment mode

bit 3-2 **Unimplemented:** Read as ‘0’

bit 1-0 **MODE<1:0>:** DMA Channel Operating Mode Select bits
11 = One-Shot Ping-Pong modes are enabled (one block transfer from/to each DMA buffer)
10 = Continuous Ping-Pong modes are enabled
01 = One-Shot Ping-Pong modes are disabled
00 = Continuous Ping-Pong modes are disabled

6. The PPS pin mapping rules are as follows:
   - Only one “output” function can be active on a given pin at any time, regardless if it is a dedicated or remappable function (one pin, one output).
   - It is possible to assign a “remappable output” function to multiple pins and externally short or tie them together for increased current drive.
   - If any “dedicated output” function is enabled on a pin, it will take precedence over any remappable “output” function.
   - If any “dedicated digital” (input or output) function is enabled on a pin, any number of “input” remappable functions can be mapped to the same pin.
   - If any “dedicated analog” function(s) are enabled on a given pin, “digital input(s)” of any kind will all be disabled, although a single “digital output”, at the user’s cautionary discretion, can be enabled and active as long as there is no signal contention with an external analog input signal. For example, it is possible for the ADC to convert the digital output logic level, or to toggle a digital output on a comparator or ADC input provided there is no external analog input, such as for a built-in self-test.
   - Any number of “input” remappable functions can be mapped to the same pin(s) at the same time, including to any pin with a single output from either a dedicated or remappable “output”.
   - The TRISx registers control only the digital I/O output buffer. Any other dedicated or remappable active “output” will automatically override the TRISx setting. The TRISx register does not control the digital logic “input” buffer. Remappable digital “inputs” do not automatically override TRISx settings, which means that the TRISx bit must be set to input for pins with only remappable input function(s) assigned
   - All analog pins are enabled by default after any Reset and the corresponding digital input buffer on the pin is disabled. Only the Analog Pin Select registers control the digital input buffer, not the TRISx register. The user must disable the analog function on a pin using the Analog Pin Select registers in order to use any “digital input(s)” on a corresponding pin; no exceptions.

12.0 TIMER1

> **Note 1:** This data sheet summarizes the features of the dsPIC33EVXXXGM00X/10X family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Timers"** (DS70362) in the *"dsPIC33/PIC24 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).
>
> **2:** Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The Timer1 module is a 16-bit timer that can operate as a free-running, interval timer/counter.

The Timer1 module has the following unique features over other timers:

- Can be Operated in Asynchronous Counter mode from an External Clock Source
- The Timer1 External Clock Input (T1CK) can Optionally be Synchronized to the Internal Device Clock and the Clock Synchronization is Performed after the Prescaler

A block diagram of Timer1 is shown in Figure 12-1.

The Timer1 module can operate in one of the following modes:

- Timer mode
- Gated Timer mode
- Synchronous Counter mode
- Asynchronous Counter mode

In Timer and Gated Timer modes, the input clock is derived from the internal instruction cycle clock (FCY). In Synchronous and Asynchronous Counter modes, the input clock is derived from the external clock input at the T1CK pin.

The Timer modes are determined by the following bits:

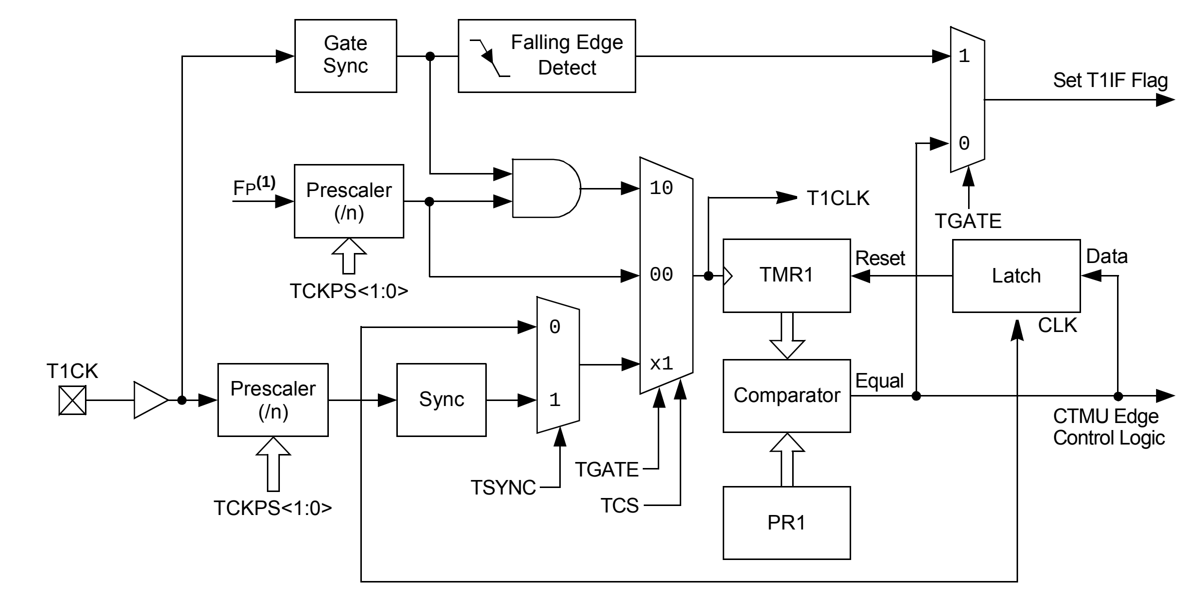
- Timer Clock Source Control bit (TCS): T1CON<1>
- Timer Synchronization Control bit (TSYNC): T1CON<2>
- Timer Gate Control bit (TGATE): T1CON<6>

Timer control bit settings for different operating modes are given in Table 12-1.

TABLE 12-1: TIMER MODE SETTINGS

Mode	TCS	TGATE	TSYNC
Timer	0	0	x
Gated Timer	0	1	x
Synchronous Counter	1	x	1
Asynchronous Counter	1	x	0

FIGURE 12-1: 16-BIT TIMER1 MODULE BLOCK DIAGRAM



Note 1: FP is the peripheral clock.

BUFFER 22-7: CANx MESSAGE BUFFER WORD 6

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
Byte 7<15:8>							
bit 15							bit 8

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
Byte 6<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-8 **Byte 7<15:8>:** CANx Message Byte 7 bits

bit 7-0 **Byte 6<7:0>:** CANx Message Byte 6 bits

BUFFER 22-8: CANx MESSAGE BUFFER WORD 7

U-0	U-0	U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
—	—	—	FILHIT<4:0>(1)				
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-13 **Unimplemented:** Read as ‘0’

bit 12-8 **FILHIT<4:0>:** Filter Hit Code bits(1)
Encodes number of filter that resulted in writing this buffer.

bit 7-0 **Unimplemented:** Read as ‘0’

Note 1: Only written by module for receive buffers, unused for transmit buffers.

REGISTER 24-6: ADxCHS0: ADCx INPUT CHANNEL 0 SELECT REGISTER

R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CH0NB	—	CH0SB5(1,3)	CH0SB4(1,3)	CH0SB3(1,3)	CH0SB2(1,3)	CH0SB1(1,3)	CH0SB0(1,3)
bit 15							bit 8

R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CH0NA	—	CH0SA5(1,3)	CH0SA4(1,3)	CH0SA3(1,3)	CH0SA2(1,3)	CH0SA1(1,3)	CH0SA0(1,3)
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **CH0NB:** Channel 0 Negative Input Select for Sample MUX B bit
1 = Channel 0 negative input is AN1(1)
0 = Channel 0 negative input is VREFL

bit 14 **Unimplemented:** Read as '0'

bit 13-8 **CH0SB<5:0>:** Channel 0 Positive Input Select for Sample MUX B bits(1,3)
111111 = Channel 0 positive input is AN63
111110 = Channel 0 positive input is AN62
111101 = Channel 0 positive input is AN61 (internal band gap voltage)
•
•
•
011111 = Channel 0 positive input is AN31
011110 = Channel 0 positive input is AN30
•
•
•
000001 = Channel 0 positive input is AN1
000000 = Channel 0 positive input is AN0 (Op Amp 2)(2)

bit 7 **CH0NA:** Channel 0 Negative Input Select for Sample MUX A bit
1 = Channel 0 negative input is AN1(1)
0 = Channel 0 negative input is VREFL

bit 6 **Unimplemented:** Read as '0'

Note 1: AN0 to AN7 are repurposed when comparator and op amp functionality are enabled. See Figure 24-1 to determine how enabling a particular op amp or comparator affects selection choices for Channels 1, 2 and 3.

2: If the op amp is selected (OPAEN bit (CMxCON<10>) = 1), the OAx input is used; otherwise, the ANx input is used.

3: See the **"Pin Diagrams"** section for the available analog channels for each device.

REGISTER 24-8: ADxCSSL: ADCx INPUT SCAN SELECT REGISTER LOW[1,2]

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CSS<15:8>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CSS<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-0 **CSS<15:0>:** ADCx Input Scan Selection bits
1 = Selects ANx for input scan
0 = Skips ANx for input scan

Note 1: On devices with less than 16 analog inputs, all bits in this register can be selected by the user application. However, inputs selected for scan without a corresponding input on the device convert V_{REFL}.

2: CSSx = ANx, where ‘x’ = 0-5.

27.2 User OTP Memory

Locations, 800F80h-800FFEh, are a One-Time-Programmable (OTP) memory area. The user OTP words can be used for storing product information, such as serial numbers, system manufacturing dates, manufacturing lot numbers and other application-specific information.

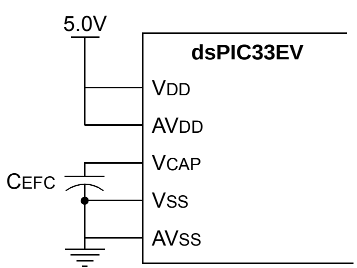
27.3 On-Chip Voltage Regulator

All of the dsPIC33EVXXXGM00X/10X family devices power their core digital logic at a nominal 1.8V. This can create a conflict for designs that are required to operate at a higher typical voltage, such as 5.0V. To simplify system design, all devices in the dsPIC33EVXXXGM00X/10X family incorporate an on-chip regulator that allows the device to run its core logic from VDD.

The regulator provides power to the core from the other VDD pins. A low-ESR (less than 1 Ohm) capacitor (such as tantalum or ceramic) must be connected to the VCAP pin (see Figure 27-1). This helps to maintain the stability of the regulator. The recommended value for the filter capacitor is provided in Table 30-5, located in **Section 30.0 "Electrical Characteristics"**.

Note:	It is important for the low-ESR capacitor to be placed as close as possible to the VCAP pin.

FIGURE 27-1: CONNECTIONS FOR THE ON-CHIP VOLTAGE REGULATOR(1,2,3)



Note 1: These are typical operating voltages. Refer to Table 30-4 located in **Section 30.1 "DC Characteristics"** for the full operating ranges of VDD and VCAP.

2: It is important for the low-ESR capacitor to be placed as close as possible to the VCAP pin.

3: Typical VCAP pin voltage = 1.8V when VDD ≥ VDDMIN.

27.4 Brown-out Reset (BOR)

The Brown-out Reset (BOR) module is based on an internal voltage reference circuit that monitors the regulated supply voltage, VCAP. The main purpose of the BOR module is to generate a device Reset when a brown-out condition occurs. Brown-out conditions are generally caused by glitches on the AC mains (for example, missing portions of the AC cycle waveform due to bad power transmission lines or voltage sags due to excessive current draw when a large inductive load is turned on).

A BOR generates a Reset pulse, which resets the device. The BOR selects the clock source based on the device Configuration bit values (FNOSC<2:0> and POSCMD<1:0>).

If an oscillator mode is selected, the BOR activates the Oscillator Start-up Timer (OST). The system clock is held until OST expires. If the PLL is used, the clock is held until the LOCK bit (OSCCON<5>) is '1'.

Concurrently, the Power-up Timer (PWRT) Time-out (TPWRT) is applied before the internal Reset is released. If TPWRT = 0 and a crystal oscillator is being used, then a nominal delay of TFSCM is applied. The total delay in this case is TFSCM. Refer to Parameter SY35 in Table 30-22 of **Section 30.0 "Electrical Characteristics"** for specific TFSCM values.

The BOR status bit (RCON<1>) is set to indicate that a BOR has occurred. The BOR circuit continues to operate while in Sleep or Idle mode and resets the device should VDD fall below the BOR threshold voltage.

27.5 Watchdog Timer (WDT)

For dsPIC33EVXXXGM00X/10X family devices, the WDT is driven by the LPRC oscillator. When the WDT is enabled, the clock source is also enabled.

27.5.1 PRESCALER/POSTSCALER

The nominal WDT clock source from LPRC is 32 kHz. This feeds a prescaler that can be configured for either 5-bit (divide-by-32) or 7-bit (divide-by-128) operation. The prescaler is set by the WDTPRE Configuration bit. With a 32 kHz input, the prescaler yields a WDT Time-out Period (T_{WDT}), as shown in Parameter SY12 in Table 30-22.

A variable postscaler divides down the WDT prescaler output and allows for a wide range of time-out periods. The postscaler is controlled by the WDTPOST<3:0> Configuration bits (FWDT<3:0>), which allow the selection of 16 settings, from 1:1 to 1:32,768. Using the prescaler and postscaler, time-out periods ranging from 1 ms to 131 seconds can be achieved.

The WDT, prescaler and postscaler are reset:

- On any device Reset
- On the completion of a clock switch, whether invoked by software (i.e., setting the OSWEN bit after changing the NOSCx bits) or by hardware (i.e., Fail-Safe Clock Monitor)
- When a PWRSAV instruction is executed (i.e., Sleep or Idle mode is entered)
- When the device exits Sleep or Idle mode to resume normal operation
- By a CLRWDT instruction during normal execution

Note:	The CLRWDT and PWRSAV instructions clear the prescaler and postscaler counts when executed.

27.5.2 SLEEP AND IDLE MODES

If the WDT is enabled, it continues to run during Sleep or Idle modes. When the WDT time-out occurs, the device wakes the device and code execution continues from where the PWRSAV instruction was executed. The corresponding SLEEP or IDLE bit (RCON<3:2>) needs to be cleared in software after the device wakes up.

27.5.3 ENABLING WDT

The WDT is enabled or disabled by the FWDTEN<1:0> Configuration bits in the FWDT Configuration register. When the FWDTEN<1:0> Configuration bits are set, the WDT is always enabled.

The WDT can be optionally controlled in software when the FWDTENx Configuration bits have been programmed to ‘00’. The WDT is enabled in software by setting the SWDTEN control bit (RCON<5>). The SWDTEN control bit is cleared on any device Reset. The software WDT option allows the user application to enable the WDT for critical code segments and disable the WDT during non-critical segments for maximum power savings.

The WDT flag bit, WDTO (RCON<4>), is not automatically cleared following a WDT time-out. To detect subsequent WDT events, the flag must be cleared in software.

27.5.4 WDT WINDOW

The Watchdog Timer has an optional Windowed mode enabled by programming the WINDIS bit in the WDT Configuration register (FWDT<7>). In the Windowed mode (WINDIS = 0), the WDT should be cleared based on the settings in the programmable Watchdog Timer Window (WDTWIN<1:0>) select bits.

FIGURE 27-2: WDT BLOCK DIAGRAM

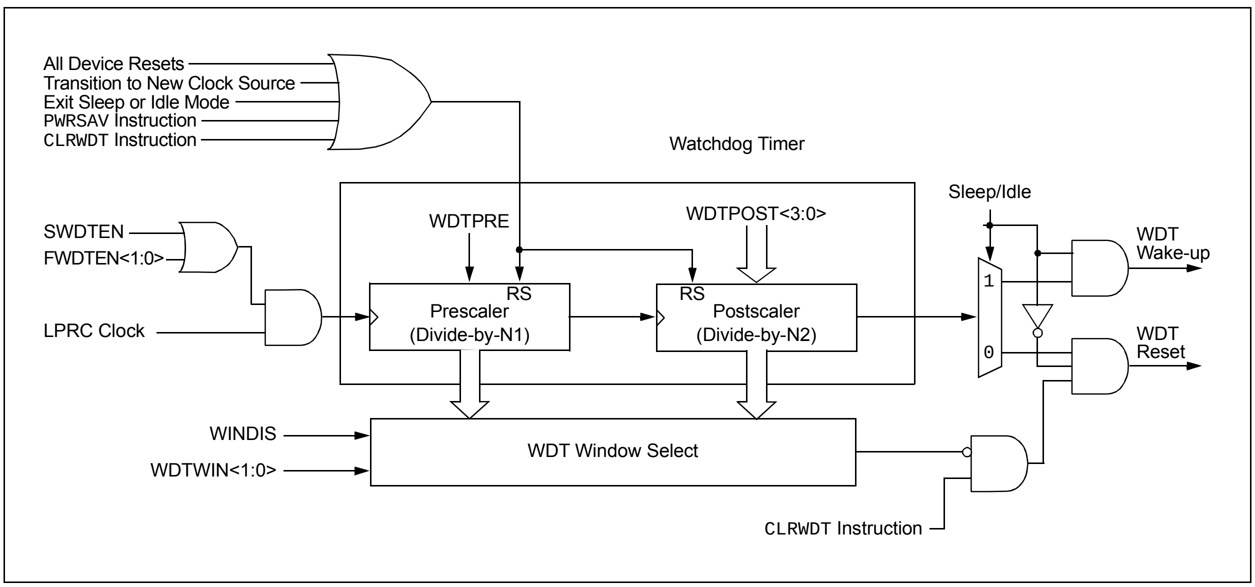


TABLE 28-2: INSTRUCTION SET OVERVIEW (CONTINUED)

Base Instr #	Assembly Mnemonic	Assembly Syntax	Description	# of Words	# of Cycles	Status Flags Affected
25	CTXTSWP	CTXTSWP #lit3	Switch CPU register context to context defined by lit3	1	2	None
		CTXTSWP Wn	Switch CPU register context to context defined by Wn	1	2	None
26	DAW	DAW Wn	Wn = decimal adjust Wn	1	1	C
27	DEC	DEC f	f = f – 1	1	1	C,DC,N,OV,Z
		DEC f,WREG	WREG = f – 1	1	1	C,DC,N,OV,Z
		DEC Ws,Wd	Wd = Ws – 1	1	1	C,DC,N,OV,Z
28	DEC2	DEC2 f	f = f – 2	1	1	C,DC,N,OV,Z
		DEC2 f,WREG	WREG = f – 2	1	1	C,DC,N,OV,Z
		DEC2 Ws,Wd	Wd = Ws – 2	1	1	C,DC,N,OV,Z
29	DISI	DISI #lit14	Disable Interrupts for k instruction cycles	1	1	None
30	DIV	DIV.S Wm,Wn	Signed 16/16-bit Integer Divide	1	18	N,Z,C,OV
		DIV.SD Wm,Wn	Signed 32/16-bit Integer Divide	1	18	N,Z,C,OV
		DIV.U Wm,Wn	Unsigned 16/16-bit Integer Divide	1	18	N,Z,C,OV
		DIV.UD Wm,Wn	Unsigned 32/16-bit Integer Divide	1	18	N,Z,C,OV
31	DIVF	DIVF Wm,Wn	Signed 16/16-bit Fractional Divide	1	18	N,Z,C,OV
32	DO	DO #lit15,Expr	Do code to PC + Expr, lit15 + 1 times	2	2	None
		DO Wn,Expr	Do code to PC + Expr, (Wn) + 1 times	2	2	None
33	ED	ED Wm*Wm,Acc,Wx,Wy,Wxd	Euclidean Distance (no accumulate)	1	1	OA,OB,OAB, SA,SB,SAB
34	EDAC	EDAC Wm*Wm,Acc,Wx,Wy,Wxd	Euclidean Distance	1	1	OA,OB,OAB, SA,SB,SAB
35	EXCH	EXCH Wns,Wnd	Swap Wns with Wnd	1	1	None
36	FBCL	FBCL Ws,Wnd	Find Bit Change from Left (MSb) Side	1	1	C
37	FF1L	FF1L Ws,Wnd	Find First One from Left (MSb) Side	1	1	C
38	FF1R	FF1R Ws,Wnd	Find First One from Right (LSb) Side	1	1	C
39	GOTO	GOTO Expr	Go to address	2	4	None
		GOTO Wn	Go to indirect	1	4	None
		GOTO.L Wn	Go to indirect (long address)	1	4	None
40	INC	INC f	f = f + 1	1	1	C,DC,N,OV,Z
		INC f,WREG	WREG = f + 1	1	1	C,DC,N,OV,Z
		INC Ws,Wd	Wd = Ws + 1	1	1	C,DC,N,OV,Z
41	INC2	INC2 f	f = f + 2	1	1	C,DC,N,OV,Z
		INC2 f,WREG	WREG = f + 2	1	1	C,DC,N,OV,Z
		INC2 Ws,Wd	Wd = Ws + 2	1	1	C,DC,N,OV,Z
42	IOR	IOR f	f = f .IOR. WREG	1	1	N,Z
		IOR f,WREG	WREG = f .IOR. WREG	1	1	N,Z
		IOR #lit10,Wn	Wd = lit10 .IOR. Wd	1	1	N,Z
		IOR Wb,Ws,Wd	Wd = Wb .IOR. Ws	1	1	N,Z
		IOR Wb,#lit5,Wd	Wd = Wb .IOR. lit5	1	1	N,Z
43	LAC	LAC Wso,#Slit4,Acc	Load Accumulator	1	1	OA,OB,OAB, SA,SB,SAB
44	LNK	LNK #lit14	Link Frame Pointer	1	1	SFA
45	LSR	LSR f	f = Logical Right Shift f	1	1	C,N,OV,Z
		LSR f,WREG	WREG = Logical Right Shift f	1	1	C,N,OV,Z
		LSR Ws,Wd	Wd = Logical Right Shift Ws	1	1	C,N,OV,Z
		LSR Wb,Wns,Wnd	Wnd = Logical Right Shift Wb by Wns	1	1	N,Z
		LSR Wb,#lit5,Wnd	Wnd = Logical Right Shift Wb by lit5	1	1	N,Z

Note: Read and Read-Modify-Write (e.g., bit operations and logical operations) on non-CPU SFRs incur an additional instruction cycle.

TABLE 28-2: INSTRUCTION SET OVERVIEW (CONTINUED)

Base Instr #	Assembly Mnemonic	Assembly Syntax	Description	# of Words	# of Cycles	Status Flags Affected
46	MAC	MAC Wm*Wn,Acc,Wx,Wxd,Wy,Wyd,AWB	Multiply and Accumulate	1	1	OA,OB,OAB, SA,SB,SAB
		MAC Wm*Wm,Acc,Wx,Wxd,Wy,Wyd	Square and Accumulate	1	1	OA,OB,OAB, SA,SB,SAB
47	MOV	MOV f,Wn	Move f to Wn	1	1	None
		MOV f	Move f to f	1	1	None
		MOV f,WREG	Move f to WREG	1	1	None
		MOV #lit16,Wn	Move 16-bit literal to Wn	1	1	None
		MOV.b #lit8,Wn	Move 8-bit literal to Wn	1	1	None
		MOV Wn,f	Move Wn to f	1	1	None
		MOV Wso,Wdo	Move Ws to Wd	1	1	None
		MOV WREG,f	Move WREG to f	1	1	None
		MOV.D Wns,Wd	Move Double from W(ns):W(ns + 1) to Wd	1	2	None
		MOV.D Ws,Wnd	Move Double from Ws to W(nd + 1):W(nd)	1	2	None
48	MOVPAG	MOVPAG #lit10,DSRPAG	Move 10-bit literal to DSRPAG	1	1	None
		MOVPAG #lit9,DSWPAG	Move 9-bit literal to DSWPAG	1	1	None
		MOVPAG #lit8,TBLPAG	Move 8-bit literal to TBLPAG	1	1	None
		MOVPAGW Ws, DSRPAG	Move Ws<9:0> to DSRPAG	1	1	None
		MOVPAGW Ws, DSWPAG	Move Ws<8:0> to DSWPAG	1	1	None
		MOVPAGW Ws, TBLPAG	Move Ws<7:0> to TBLPAG	1	1	None
49	MOVSAC	MOVSAC Acc,Wx,Wxd,Wy,Wyd,AWB	Prefetch and store accumulator	1	1	None
50	MPY	MPY Wm*Wn,Acc,Wx,Wxd,Wy,Wyd	Multiply Wm by Wn to Accumulator	1	1	OA,OB,OAB, SA,SB,SAB
		MPY Wm*Wm,Acc,Wx,Wxd,Wy,Wyd	Square Wm to Accumulator	1	1	OA,OB,OAB, SA,SB,SAB
51	MPY.N	MPY.N Wm*Wn,Acc,Wx,Wxd,Wy,Wyd	-(Multiply Wm by Wn) to Accumulator	1	1	None
52	MSC	MSC Wm*Wm,Acc,Wx,Wxd,Wy,Wyd,AWB	Multiply and Subtract from Accumulator	1	1	OA,OB,OAB, SA,SB,SAB

Note: Read and Read-Modify-Write (e.g., bit operations and logical operations) on non-CPU SFRs incur an additional instruction cycle.

29.0 DEVELOPMENT SUPPORT

The PIC® microcontrollers (MCU) and dsPIC® digital signal controllers (DSC) are supported with a full range of software and hardware development tools:

- Integrated Development Environment
  - MPLAB® X IDE Software
- Compilers/Assemblers/Linkers
  - MPLAB XC Compiler
  - MPASM™ Assembler
  - MPLINK™ Object Linker/ MPLIB™ Object Librarian
  - MPLAB Assembler/Linker/Librarian for Various Device Families
- Simulators
  - MPLAB X SIM Software Simulator
- Emulators
  - MPLAB REAL ICE™ In-Circuit Emulator
- In-Circuit Debuggers/Programmers
  - MPLAB ICD 3
  - PICkit™ 3
- Device Programmers
  - MPLAB PM3 Device Programmer
- Low-Cost Demonstration/Development Boards, Evaluation Kits and Starter Kits
- Third-party development tools

29.1 MPLAB X Integrated Development Environment Software

The MPLAB X IDE is a single, unified graphical user interface for Microchip and third-party software, and hardware development tool that runs on Windows®, Linux and Mac OS® X. Based on the NetBeans IDE, MPLAB X IDE is an entirely new IDE with a host of free software components and plug-ins for high-performance application development and debugging. Moving between tools and upgrading from software simulators to hardware debugging and programming tools is simple with the seamless user interface.

With complete project management, visual call graphs, a configurable watch window and a feature-rich editor that includes code completion and context menus, MPLAB X IDE is flexible and friendly enough for new users. With the ability to support multiple tools on multiple projects with simultaneous debugging, MPLAB X IDE is also suitable for the needs of experienced users.

Feature-Rich Editor:

- Color syntax highlighting
- Smart code completion makes suggestions and provides hints as you type
- Automatic code formatting based on user-defined rules
- Live parsing

User-Friendly, Customizable Interface:

- Fully customizable interface: toolbars, toolbar buttons, windows, window placement, etc.
- Call graph window

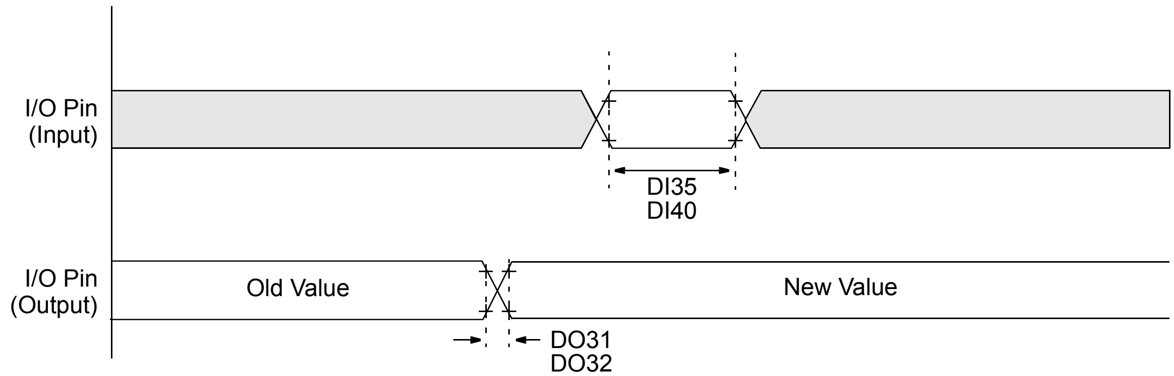
Project-Based Workspaces:

- Multiple projects
- Multiple tools
- Multiple configurations
- Simultaneous debugging sessions

File History and Bug Tracking:

- Local file history feature
- Built-in support for Bugzilla issue tracker

FIGURE 30-3: I/O TIMING CHARACTERISTICS



Note: Refer to Figure 30-1 for load conditions.

TABLE 30-21: I/O TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 4.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ.(1)**	**Max.**	**Units**	**Conditions**
DO31	TIOR	Port Output Rise Time	—	5	10	ns	
DO32	TIOF	Port Output Fall Time	—	5	10	ns	
DI35	TINP	INTx Pin High or Low Time (input)	20	—	—	ns	
DI40	TRBP	CNx High or Low Time (input)	2	—	—	TCY	

Note 1: Data in “Typ.” column is at 5.0V, +25°C unless otherwise stated.

FIGURE 30-4: BOR AND MASTER CLEAR RESET TIMING CHARACTERISTICS

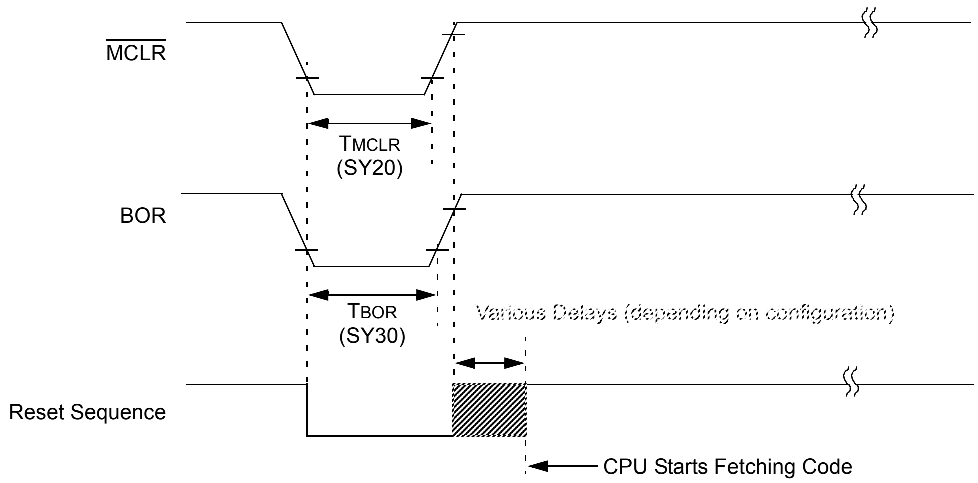
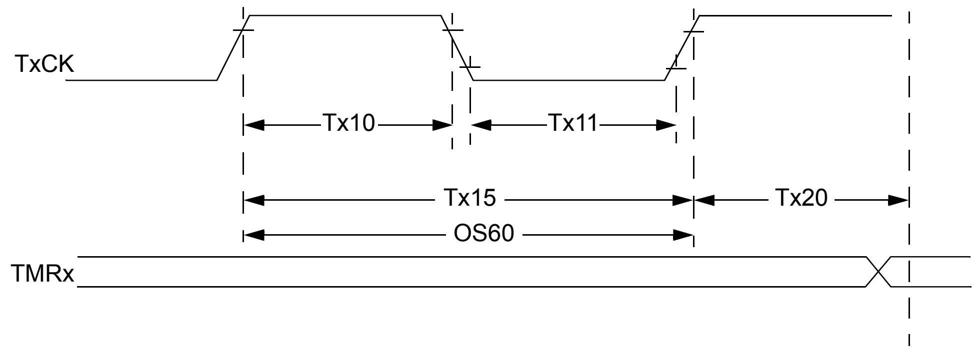


FIGURE 30-6: TIMER1-TIMER5 EXTERNAL CLOCK TIMING CHARACTERISTICS



Note: Refer to Figure 30-1 for load conditions.

TABLE 30-23: TIMER1 EXTERNAL CLOCK TIMING REQUIREMENTS[(1)]

AC CHARACTERISTICS				Standard Operating Conditions: 4.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic[(2)]**		**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
TA10	TTXH	T1CK High Time	Synchronous mode	Greater of: 20 or (TCY + 20)/N	—	—	ns	Must also meet Parameter TA15, N = Prescaler Value (1, 8, 64, 256)
			Asynchronous mode	35	—	—	ns	
TA11	TTXL	T1CK Low Time	Synchronous mode	Greater of: 20 or (TCY + 20)/N	—	—	ns	Must also meet Parameter TA15, N = Prescaler Value (1, 8, 64, 256)
			Asynchronous mode	10	—	—	ns	
TA15	TTXP	T1CK Input Period	Synchronous mode	Greater of: 40 or (2 TCY + 40)/N	—	—	ns	N = Prescaler Value (1, 8, 64, 256)
OS60	Ft1	T1CK Oscillator Input Frequency Range (oscillator enabled by setting TCS (T1CON<1>) bit)		DC	—	50	kHz	
TA20	TCKEXTMRL	Delay from External T1CK Clock Edge to Timer Increment		0.75 TCY + 40	—	1.75 TCY + 40	ns	

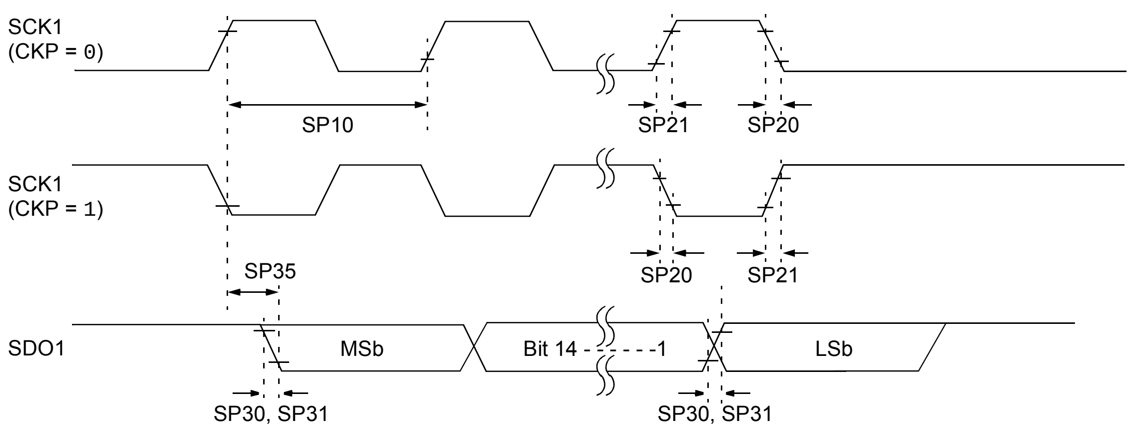
Note 1: Timer1 is a Type A.

2: These parameters are characterized but not tested in manufacturing.

TABLE 30-38: SPI1 MAXIMUM DATA/CLOCK RATE SUMMARY

AC CHARACTERISTICS			Standard Operating Conditions: 4.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Maximum Data Rate	**Master Transmit Only (Half-Duplex)**	**Master Transmit/Receive (Full-Duplex)**	**Slave Transmit/Receive (Full-Duplex)**	**CKE**	**CKP**	**SMP**
25 MHz	Table 30-39	—	—	0,1	0,1	0,1
25 MHz	—	Table 30-40	—	1	0,1	1
25 MHz	—	Table 30-41	—	0	0,1	1
25 MHz	—	—	Table 30-42	1	0	0
25 MHz	—	—	Table 30-43	1	1	0
25 MHz	—	—	Table 30-44	0	1	0
25 MHz	—	—	Table 30-45	0	0	0

FIGURE 30-20: SPI1 MASTER MODE (HALF-DUPLEX, TRANSMIT ONLY, CKE = 0) TIMING CHARACTERISTICS



Note: Refer to Figure 30-1 for load conditions.

TABLE 30-50: OP AMP/COMPARATOR x SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions (see Note 3): 4.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ.(1)**	**Max.**	**Units**	**Conditions**
		Comparator AC Characteristics					
CM10	TRESP	Response Time	—	19	80	ns	V+ input step of 100 mV, V- input held at VDD/2
CM11	TMC2OV	Comparator Mode Change to Output Valid	—	—	10	µs	
		Comparator DC Characteristics					
CM30	VOFFSET	Comparator Offset Voltage	-80	±60	80	mV	
CM31	VHYST	Input Hysteresis Voltage	—	30	—	mV	
CM32	TRISE/ TFALL	Comparator Output Rise/Fall Time	—	20	—	ns	1 pF load capacitance on input
CM33	VGAIN	Open-Loop Voltage Gain	—	90	—	db	
CM34	VICM	Input Common-Mode Voltage	AVSS	—	AVDD	V	
		Op Amp AC Characteristics					
CM20	SR	Slew Rate	—	9	—	V/µs	10 pF load
CM21	PM	Phase Margin	—	35	—	°C	G = 100V/V, 10 pF load
CM22	GM	Gain Margin	—	20	—	db	G = 100V/V, 10 pF load
CM23	GBW	Gain Bandwidth	—	10	—	MHz	10 pF load
		Op Amp DC Characteristics					
CM40	VCMR	Common-Mode Input Voltage Range	AVSS	—	AVDD	V	
CM41	CMRR	Common-Mode Rejection Ratio	—	45	—	db	VCM = AVDD/2
CM42	VOFFSET	Op Amp Offset Voltage	-50	±6	50	mV	
CM43	VGAIN	Open-Loop Voltage Gain	—	90	—	db	
CM44	IOS	Input Offset Current	—	—	—	—	See pad leakage currents in Table 30-10
CM45	IB	Input Bias Current	—	—	—	—	See pad leakage currents in Table 30-10
CM46	IOUT	Output Current	—	—	420	µA	With minimum value of RFEEDBACK (CM48)
CM48	RFEEDBACK	Feedback Resistance Value	8	—	—	kΩ	**Note 2**
CM49a	VOUT	Output Voltage	AVSS + 0.075	—	AVDD – 0.075	V	IOUT = 420 µA

Note 1: Data in "Typ." column is at 5.0V, +25°C unless otherwise stated.

2: Resistances can vary by ±10% between op amps.

3: Device is functional at VBORMIN < VDD < VDDMIN, but will have degraded performance. Device functionality is tested, but not characterized. Analog modules: ADC, op amp/comparator and comparator voltage reference, will have degraded performance. Refer to Parameter BO10 in Table 30-12 for the minimum and maximum BOR values.

FIGURE 33-7: TYPICAL IIDLE vs. VDD (EC MODE, 20 MIPS)

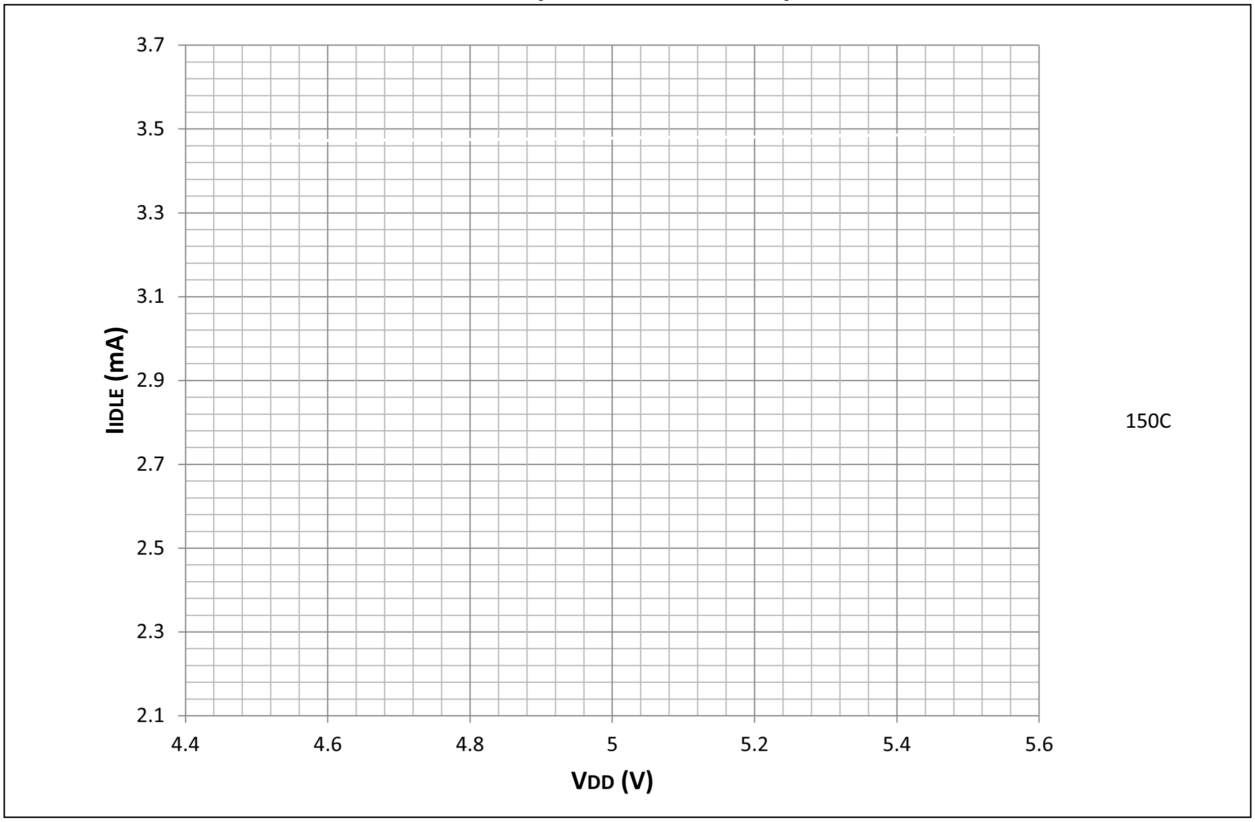
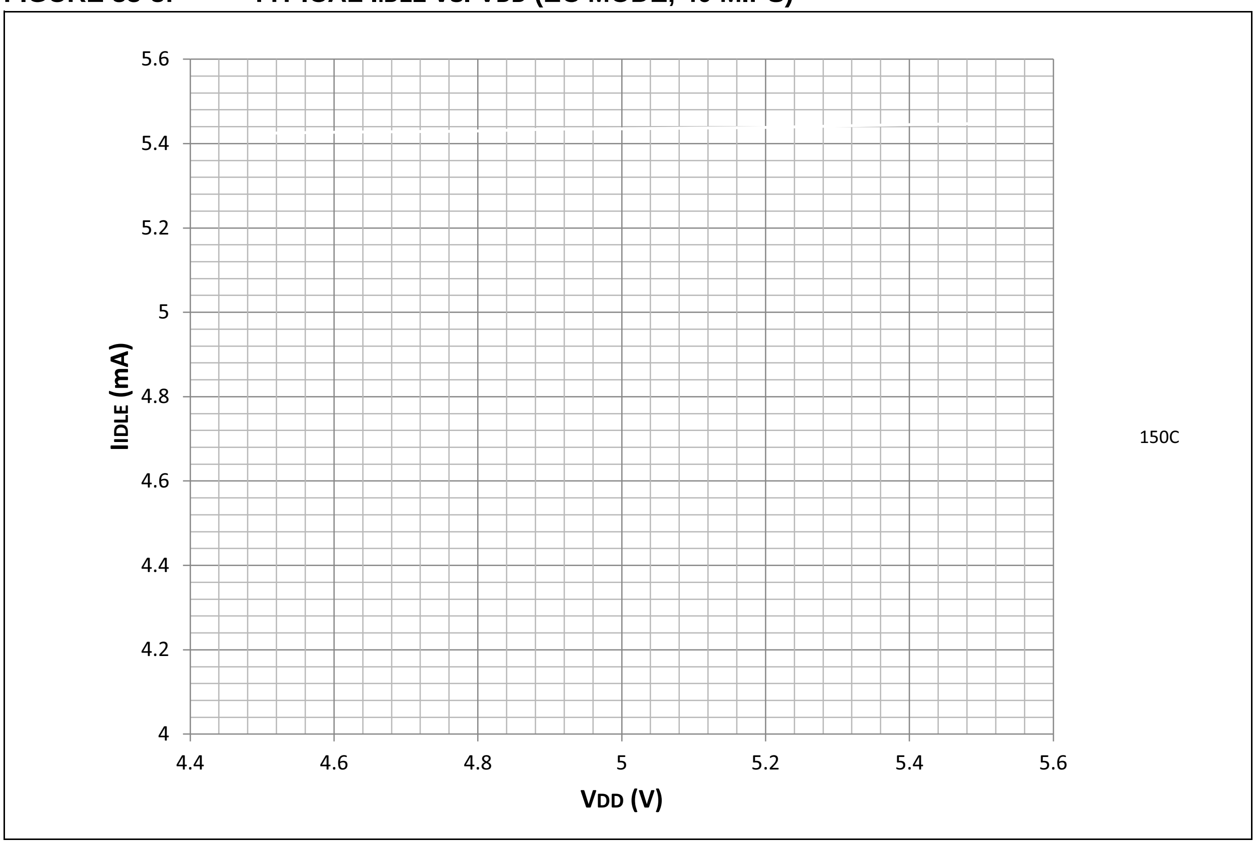
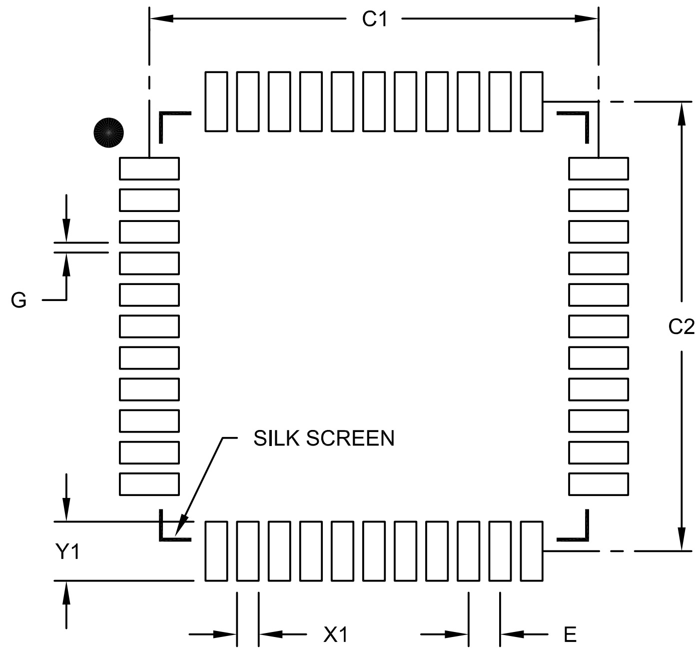


FIGURE 33-8: TYPICAL IIDLE vs. VDD (EC MODE, 40 MIPS)



44-Lead Plastic Thin Quad Flatpack (PT) 10X10X1 mm Body, 2.00 mm Footprint [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.80 BSC		
Contact Pad Spacing	C1		11.40	
Contact Pad Spacing	C2		11.40	
Contact Pad Width (X44)	X1			0.55
Contact Pad Length (X44)	Y1			1.50
Distance Between Pads	G	0.25		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2076B